

What's New at SEMI



Government Funding
UCLA and SEMI Win NIST Funding to Produce Heterogeneous Integration Roadmap
The roadmap will build upon the International Technology Roadmap for Semiconductors (ITRS) and Heterogeneous Integration ...



Conference
ISS Europe 2022 to Highlight Supply Chain Resilience, Sustainability and Workforce Diversity
SEMI ISS Europe will gather industry experts, executives and researchers for microelectronics market projections and insights ...



Conference
ISS Europe 2022: Imec Deep Tech Drives Semiconductor Sustainability
When it comes to developing new semiconductor manufacturing processes, we also have to look beyond power, performance, area ...



Conference
SEMI 3D & Systems Summit to Spotlight Trends in High-Performance, Energy-Efficient Applications
Leading experts in 3D integration and systems for semiconductor manufacturing applications will gather at the annual SEMI 3D ...



Conference
Innovative MEMS and Sensors Solutions for New Products and Processing Unveiled at MSTC 2022
The latest MEMS and sensors advancements in markets ranging from displays to biotech and in key areas of manufacturing including ...



Sustainability
Celebrating SEMI Members as They Reach New Milestones in Q1 2022
Connecting the entire electronics manufacturing and design supply chain to help drive innovation and industry growth would not be ...



SEMI-Related
Robots and Humans Make Murals Together
Human design and robotic labor generate unique plaster designs.

Events/Webinars

May 18, 2022	MEMS and Sensors Packaging for Limitless Applications Virtual Pacific Standard Time
May 18, 2022	WORKFORCE SHORTAGE—Meeting Challenges for the Semiconductor Industry Virtual Central Standard Time
May 18-31, 2022	SMC Korea 2022 Virtual Korea Standard Time

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